



Form PTO-1449

Applicant: Tanspuz, et al.

Serial No.: 10/678,010

Filing Date: October 2, 2003

For: METHOD FOR MAINTAINING SOLDER THICKNESS
IN FLIPCHIP ATTACH PACKAGING PROCESS

Sheet 1 of 1

Att'y Docket No. 11948.36

Group: 2828

2818

INFORMATION DISCLOSURE CITATIONS MADE BY APPLICANTCo-Pending Applications

Examiner Initial*	Application Number	Filing Date
<u>TH</u> A1.	10/413,668	04/14/2003

U.S. Patent Documents

Examiner Initial*	Document Number	Issue Date	Name
<u>TH</u> A2.	6,297,562	10/01/2001	Tilly
<u>TH</u> A3.	6,307,755	10/23/2001	Williams, et al.
<u>TH</u> A4.	6,391,758	05/04/2002	Lo, et al.
<u>TH</u> A5.	6,720,642	04/13/2004	Joshi, et al.
<u>TH</u> A6.	6,774,466	08/10/2004	Kijiwara, et al.

DOCS#800206-v1-Supp_IDS_1449.DOC

Examiner: TH-TH HO

Date Considered:

May 2005

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.